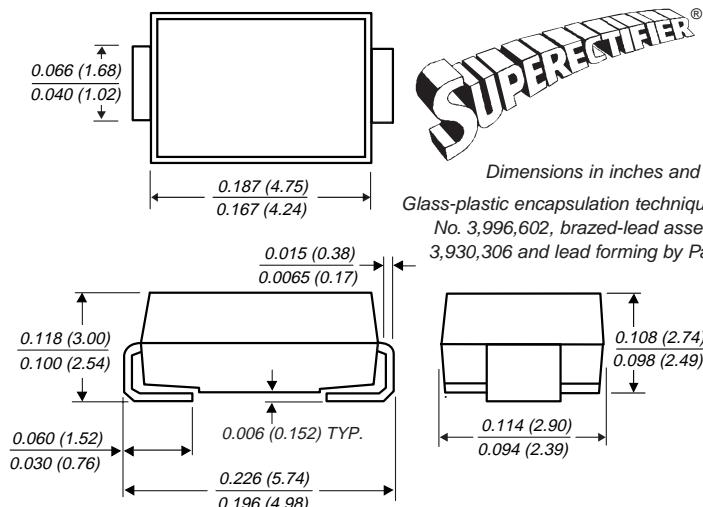
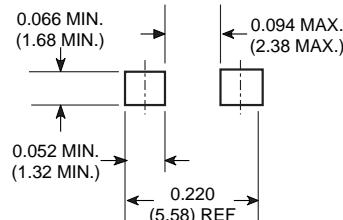



DO-214BA (GF1)

SUPERRECTIFIER®

 Dimensions in inches and (millimeters)
 Glass-plastic encapsulation technique is covered by Patent No. 3,996,602, brazed-lead assembly by Patent No. 3,930,306 and lead forming by Patent No. 5,151,846

 Reverse Voltage 50 to 1000V
 Forward Current 1.0A

Mounting Pad Layout

Features

- Plastic package has Underwriters Laboratories Flammability Classification 94V-0
- Ideal for surface mount automotive applications
- High temperature metallurgically bonded construction
- Cavity-free glass passivated junction
- Capable of meeting environmental standards of MIL-S-19500
- Built-in strain relief • Easy pick and place
- Fast switching for high efficiency
- High temperature soldering guaranteed: 450°C/5 seconds at terminals.
- Complete device submersible temperature of 265°C for 10 seconds in solder bath

Mechanical Data
Case: JEDEC DO-214BA, molded plastic over glass body

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any **Weight:** 0.0048 oz, 0.12 g

Packaging codes/options:

19/6.5K per 13" Reel (12mm Tape)

17/1.5K per 7" Reel (12mm Tape)

Maximum Ratings & Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	RGF1A	RGF1B	RGF1D	RGF1G	RGF1J	RGF1K	RGF1M	Unit
Device marking code		RA	RB	RD	RG	RJ	RK	RM	
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L = 120^\circ\text{C}$	IF(AV)					1.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM					30			A
Max. full load reverse current, full cycle average $T_A = 55^\circ\text{C}$	IR(AV)				50				μA
Typical thermal resistance ⁽¹⁾	$R_{\theta JA}$ $R_{\theta JL}$				80				$^\circ\text{C/W}$
Operating junction and storage temperature range	T _J , T _{STG}				28				
					-65 to +175				$^\circ\text{C}$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	RGF1A	RGF1B	RGF1D	RGF1G	RGF1J	RGF1K	RGF1M	Unit
Maximum instantaneous forward voltage at 1.0A	V _F				1.30				V
Maximum DC reverse current	I _R				5.0				μA
at rated DC blocking voltage					100				
Typical reverse recovery time at $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25 \text{ A}$	t _{rr}			150		250	500		ns
Typical junction capacitance at 4.0V, 1MHz	C _J				8.5				pF

Note: (1) Thermal resistance from junction to ambient and from junction to lead, P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas

RGF1A thru RGF1M

Vishay Semiconductors
formerly General Semiconductor



Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

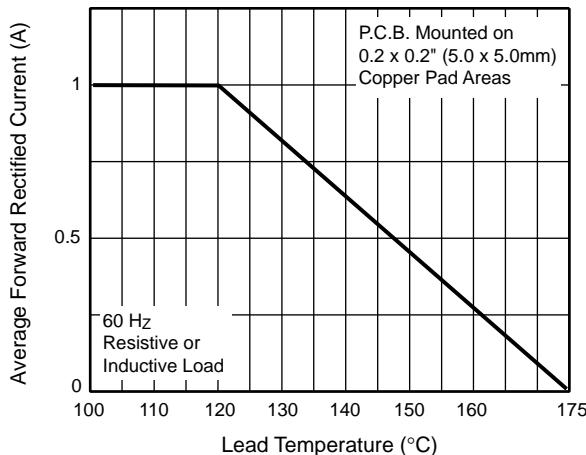


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

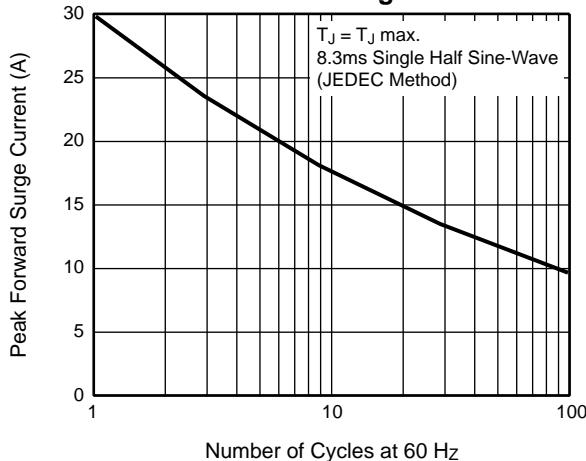


Fig. 3 – Typical Instantaneous Forward Characteristics

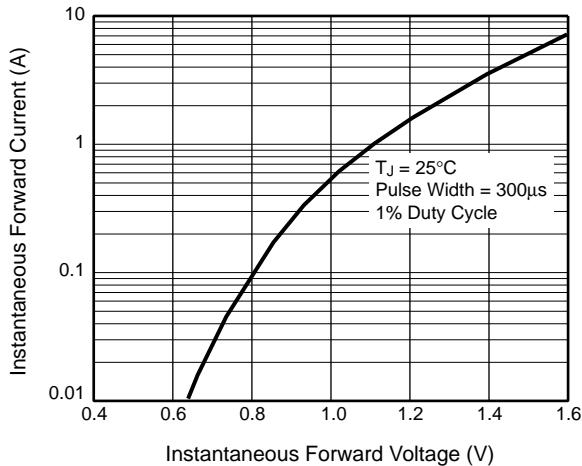


Fig. 4 – Typical Reverse Characteristics

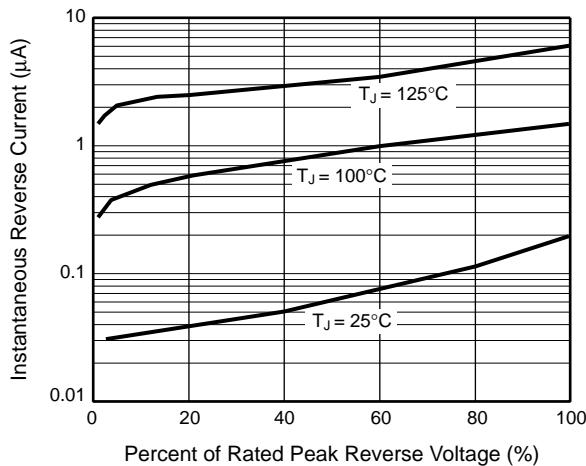


Fig. 5 – Typical Junction Capacitance

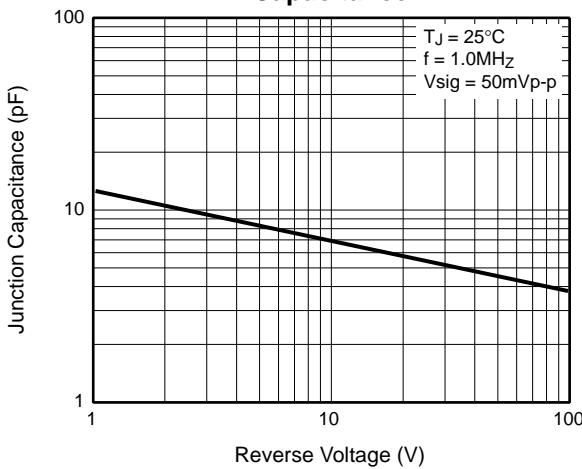


Fig. 6 – Typical Transient Thermal Impedance

